Dependable Texas Instruments Quality and Reliability

description/ordering information

These devices contain six independent inverters.

SN5404 ... J PACKAGE
SN54LS04, SN54S04 ... J OR W PACKAGE
SN7404, SN74S04 ... D, N, OR NS PACKAGE
SN74LS04 ... D, DB, N, OR NS PACKAGE
(TOP VIEW)



SN5404 . . . W PACKAGE (TOP VIEW)



SN54LS04, SN54S04 ... FK PACKAGE (TOP VIEW)



NC - No internal connection



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION

TA	PAC	KAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		Tube	SN7404N	SN7404N
	PDIP – N	Tube	SN74LS04N	SN74LS04N
		Tube	SN74S04N	SN74S04N
		Tube	SN7404D	7404
		Tape and reel	SN7404DR	7404
	0010 5	Tube	SN74LS04D	1004
0°C to 70°C	SOIC - D	Tape and reel	SN74LS04DR	LS04
		Tube	SN74S04D	004
		Tape and reel	SN74S04DR	S04
		Tape and reel	SN7404NSR	SN7404
	SOP - NS	Tape and reel	SN74LS04NSR	74LS04
		Tape and reel	SN74S04NSR	74S04
	SSOP – DB	Tape and reel	SN74LS04DBR	LS04
		Tube	SN5404J	SN5404J
		Tube	SNJ5404J	SNJ5404J
	CDIP – J	Tube	SN54LS04J	SN54LS04J
	CDIP – J	Tube	SN54S04J	SN54S04J
		Tube	SNJ54LS04J	SNJ54LS04J
-55°C to 125°C		Tube	SNJ54S04J	SNJ54S04J
		Tube	SNJ5404W	SNJ5404W
	CFP – W	Tube	SNJ54LS04W	SNJ54LS04W
		Tube	SNJ54S04W	SNJ54S04W
	1.000 F1/	Tube	SNJ54LS04FK	SNJ54LS04FK
	LCCC – FK	Tube	SNJ54S04FK	SNJ54S04FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each inverter)

`	,
INPUT	OUTPUT
Α	Υ
Н	L
L	н



logic diagram (positive logic)



schematics (each gate)



Resistor values shown are nominal.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)		
Input voltage, V _I : '04, 'S04		
'LS04		
Package thermal impedance, θ _{JA} (see Note 2	2): D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	
Storage temperature range, T _{stg}		

recommended operating conditions (see Note 3)

			SN5404		,	SN7404		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			16			16	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEGT CONDITIO			SN5404			SN7404		
PARAMETER		TEST CONDITIONS‡			TYP§	MAX	MIN	TYP§	MAX	UNIT
VIK	$V_{CC} = MIN,$	$I_{I} = -12 \text{ mA}$				-1.5			-1.5	V
Voн	$V_{CC} = MIN,$	$V_{IL} = 0.8 V$,	$I_{OH} = -0.4 \text{ mA}$	2.4	3.4		2.4	3.4		V
VOL	$V_{CC} = MIN,$	$V_{IH} = 2 V$,	$I_{OL} = 16 \text{ mA}$		0.2	0.4		0.2	0.4	V
lį	$V_{CC} = MAX$,	V _I = 5.5 V				1			1	mA
lΗ	$V_{CC} = MAX$,	V _I = 2.4 V				40			40	μΑ
I _Ι Γ	$V_{CC} = MAX$,	V _I = 0.4 V				-1.6			-1.6	mA
los¶	VCC = MAX			-20		-55	-18		-55	mA
Іссн	$V_{CC} = MAX$,	V _I = 0 V			6	12		6	12	mA
ICCL	$V_{CC} = MAX$,	V _I = 4.5 V			18	33		18	33	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[§] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[¶] Not more than one output should be shorted at a time.

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switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see Figure 1)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST C	CONDITIONS		SN5404 SN7404		UNIT
		(INFOT)	(001701)				TYP	MAX	
I	^t PLH	۸	V	P 400 O	C 15 pE		12	22	20
	^t PHL	A	ſ	$R_L = 400 \Omega$,	C _L = 15 pF		8	15	ns

recommended operating conditions (see Note 3)

		s	N54LS04	4	S	N74LS04	4	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-0.4			-0.4	mA
lOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEGT CONDITIONS!		S	SN54LS04			SN74LS04			
PARAMETER	TEST CONDITIONS†			MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT	
VIK	V _{CC} = MIN,	$I_{I} = -18 \text{ mA}$				-1.5			-1.5	V	
Voн	$V_{CC} = MIN,$	$V_{IL} = MAX$,	$I_{OH} = -0.4 \text{ mA}$	2.5	3.4		2.7	3.4		V	
	Vaa – MIN	V 2 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4			0.4	V	
V_{OL}	$V_{CC} = MIN,$ $V_{IH} = 2 V$	I _{OL} = 8 mA					0.25	0.5	V		
ΙĮ	$V_{CC} = MAX$,	V _I = 7 V				0.1			0.1	mA	
lН	$V_{CC} = MAX$,	V _I = 2.7 V				20			20	μΑ	
I _{IL}	$V_{CC} = MAX$,	V _I = 0.4 V				-0.4			-0.4	mA	
I _{OS} §	VCC = MAX		_	-20		-100	-20		-100	mA	
ІССН	V _{CC} = MAX,	V _I = 0 V			1.2	2.4		1.2	2.4	mA	
ICCL	$V_{CC} = MAX,$	V _I = 4.5 V	_		3.6	6.6		3.6	6.6	mA	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST C	CONDITIONS		N54LS04 N74LS04		UNIT
	(IIVI O1)	(0011 01)			MIN	TYP	MAX	
t _{PLH}	^	V	D. 210	C: 45 pF		9	15	
^t PHL	А	Ť	$R_L = 2 k\Omega$,	C _L = 15 pF		10	15	ns



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions (see Note 3)

		8	N54S04		9	N74S04		LINUT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
lOH	High-level output current			-1			-1	mA
lOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555				(SN54S04			N74S04		
PARAMETER		TEST CONDITION	ONSI	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$				-1.2			-1.2	V
Voн	$V_{CC} = MIN,$	$V_{IL} = 0.8 V$,	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.7	3.4		V
VOL	$V_{CC} = MIN,$	V _{IH} = 2 V,	$I_{OL} = 20 \text{ mA}$			0.5			0.5	V
ΙĮ	$V_{CC} = MAX$,	V _I = 5.5 V				1			1	mA
lН	$V_{CC} = MAX$,	V _I = 2.7 V				50			50	μΑ
Ι _Ι L	$V_{CC} = MAX$,	V _I = 0.5 V				-2			-2	mA
los§	$V_{CC} = MAX$			-40		-100	-40		-100	mA
Іссн	$V_{CC} = MAX$,	V _I = 0 V			15	24		15	24	mA
ICCL	$V_{CC} = MAX$,	V _I = 4.5 V	-		30	54		30	54	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER	PARAMETER FROM TO TEST CONDITIONS			N54S04 N74S04		UNIT		
	(INFOT)	(001-01)			MIN	TYP	MAX	
^t PLH	۸	V	$R_1 = 280 \Omega$	C _I = 15 pF		3	4.5	ns
tPHL	A	'	KL = 200 sz,	OL = 13 pr		3	5	115
tPLH .	۸	V	$R_1 = 280 \Omega$	C: - 50 pE		4.5		ns
^t PHL	А	r	NL = 200 22,	C _L = 50 pF		5		115

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION SERIES 54/74 AND 54S/74S DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. All diodes are 1N3064 or equivalent.
- C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
- E. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50~\Omega$; t_r and $t_f \leq$ 7 ns for Series 54/74 devices and t_r and $t_f \leq$ 2.5 ns for Series 54S/74S devices.
- F. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION SERIES 54LS/74LS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 - F. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50 \ \Omega$, $t_f \leq$ 1.5 ns, $t_f \leq$ 2.6 ns.
 - G. The outputs are measured one at a time, with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00105BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00105BCA	Samples
JM38510/00105BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00105BDA	Samples
JM38510/07003BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07003BCA	Samples
JM38510/07003BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07003BDA	Samples
JM38510/30003B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003B2A	Samples
JM38510/30003BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003BCA	Samples
JM38510/30003BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003BDA	Samples
JM38510/30003SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003SCA	Samples
M38510/00105BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00105BCA	Samples
M38510/00105BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00105BDA	Samples
M38510/07003BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07003BCA	Samples
M38510/07003BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07003BDA	Samples
M38510/30003B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003B2A	Samples
M38510/30003BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003BCA	Samples
M38510/30003BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003BDA	Samples
M38510/30003SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30003SCA	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN5404J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5404J	Samples
SN54LS04J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS04J	Samples
SN54S04J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S04J	Samples
SN7404D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	7404	
SN7404DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7404	Samples
SN7404N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN7404N	Samples
SN7404NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN7404N	Samples
SN74LS04D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS04	Samples
SN74LS04DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		LS04	Samples
SN74LS04DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS04	Samples
SN74LS04DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS04	Samples
SN74LS04DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS04	Samples
SN74LS04N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS04N	Samples
SN74LS04NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS04N	Samples
SN74LS04NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS04	Samples
SN74S04D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	S04	
SN74S04DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S04	Samples
SN74S04N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S04N	Samples
SN74S04NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S04N	Samples
SN74S04NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74S04	Samples
SNJ5404J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5404J	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ5404W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5404W	Samples
SNJ54LS04FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 04FK	Samples
SNJ54LS04J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS04J	Samples
SNJ54LS04W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS04W	Samples
SNJ54S04FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 04FK	Samples
SNJ54S04J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S04J	Samples
SNJ54S04W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S04W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN5404, SN54LS04, SN54LS04-SP, SN54S04, SN7404, SN74LS04, SN74S04:

Catalog: SN7404, SN74LS04, SN54LS04, SN74S04

Military: SN5404, SN54LS04, SN54S04

Space : SN54LS04-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO PI BO Cavity A0

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN7404DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS04DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LS04DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS04NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S04DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S04NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN7404DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS04DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LS04DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS04NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74S04DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74S04NSR	SOP	NS	14	2000	356.0	356.0	35.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/00105BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/07003BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/30003B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30003BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/00105BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/07003BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30003B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/30003BDA	W	CFP	14	25	506.98	26.16	6220	NA
SN7404N	N	PDIP	14	25	506	13.97	11230	4.32
SN7404N	N	PDIP	14	25	506	13.97	11230	4.32
SN7404NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN7404NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS04D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS04DG4	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS04NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS04NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74S04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S04NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74S04NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ5404W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54LS04FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS04W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54S04FK	FK	LCCC	20	55	506.98	12.06	2030	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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